

-60V P-Channel Enhancement Mode MOSFET

Description

The AP45P06NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = -60V$ $I_D = -45A$

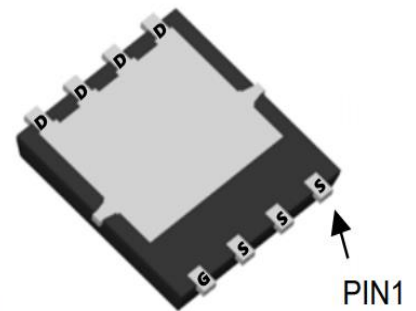
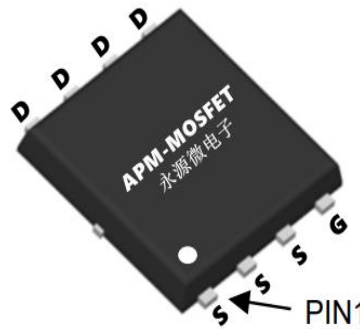
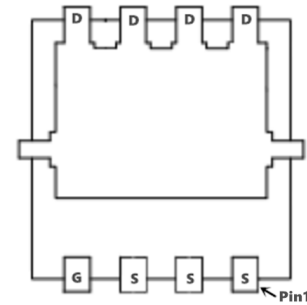
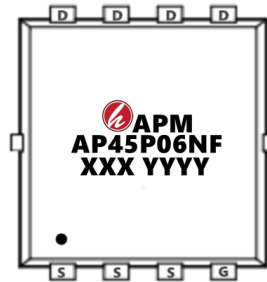
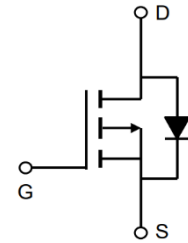
$R_{DS(ON)} < 25m\Omega$ @ $V_{GS} = -10V$ (Type: **19mΩ**)

Application

Lithium battery protection

Wireless impact

Mobile phone fast charging



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP45P06NF	PDFN5*6-8L	AP45P06NF XXX YYYY	5000

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, -V _{GS} @ -10V ¹	-45	A
I _D @T _C =100°C	Continuous Drain Current, -V _{GS} @ -10V ¹	-28	A
IDM	Pulsed Drain Current ²	-85	A
EAS	Single Pulse Avalanche Energy ³	113	mJ
IAS	Avalanche Current	47.6	A
P _D @T _C =25°C	Total Power Dissipation ⁴	52.1	W
TSTG	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-Ambient ¹	25.5	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	2.4	°C/W

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Electrical Characteristics (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-60	-68	---	V
ΔBVDSS/ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.035	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-10A	---	19	25	mΩ
		V _{GS} =-4.5V, I _D =-8A	---	26	33	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.6	-2.5	V
ΔVGS(th)	VGS(th) Temperature Coefficient		---	4.28	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =-48V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =-48V, V _{GS} =0V, T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =-10V, I _D =-18A	---	23	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	7	---	Ω
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-20V, V _{GS} =-4.5V, I _D =-12A	---	25	---	nC
Q _{gs}	Gate-Source Charge		---	6.7	---	
Q _{gd}	Gate-Drain Charge		---	5.5	---	
Td(on)	Turn-On Delay Time	V _{DD} =-15V, V _{GS} =-10V, R _G =3.3Ω, I _D =-1A	---	38	---	ns
T _r	Rise Time		---	23.6	---	
Td(off)	Turn-Off Delay Time		---	100	---	
T _f	Fall Time		---	6.8	---	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	3635	---	pF
C _{oss}	Output Capacitance		---	224	---	
Crss	Reverse Transfer Capacitance		---	141	---	
I _s	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	-35	A
ISM	Pulsed Source Current ^{2,5}		---	---	-70	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _s =-1A, T _J =25°C	---	---	-1	V

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The EAS data shows Max. rating . The test condition is VDD=-48V,VGS =-10V,L=0.1mH,IAS =-47.6A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

Typical Characteristics

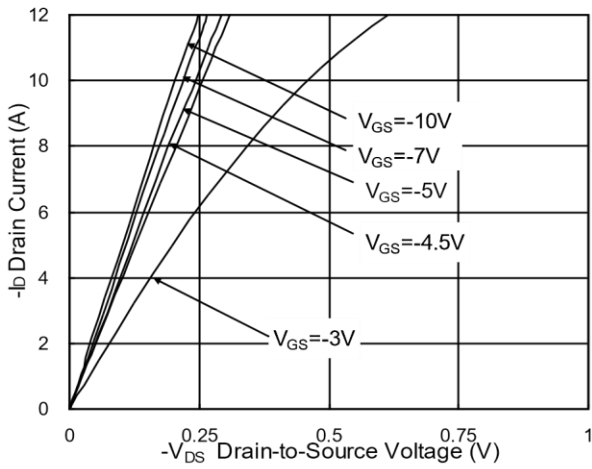


Fig.1 Typical Output Characteristics

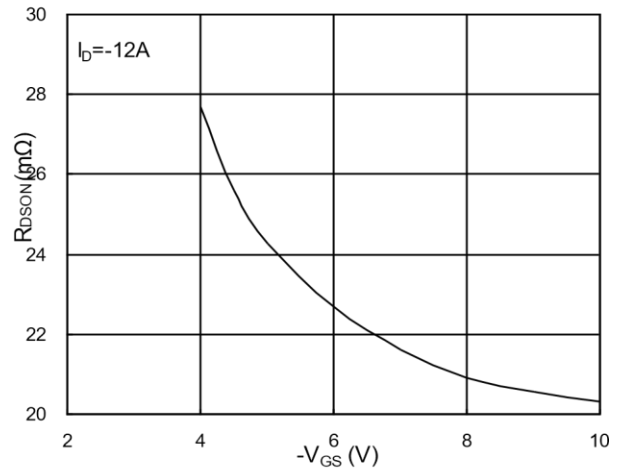


Fig.2 On-Resistance v.s Gate-Source

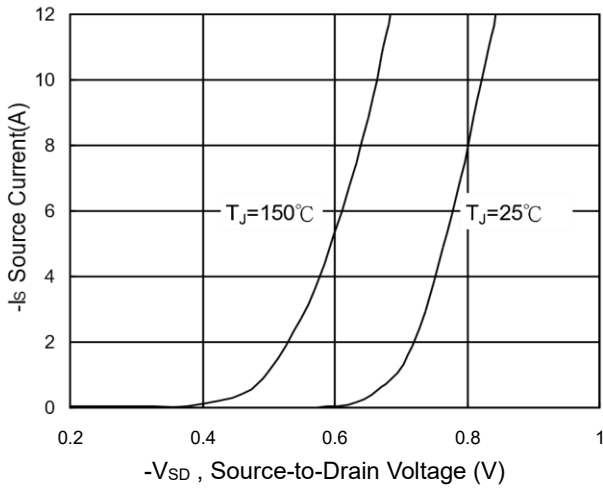


Fig.3 Forward Characteristics Of Reverse

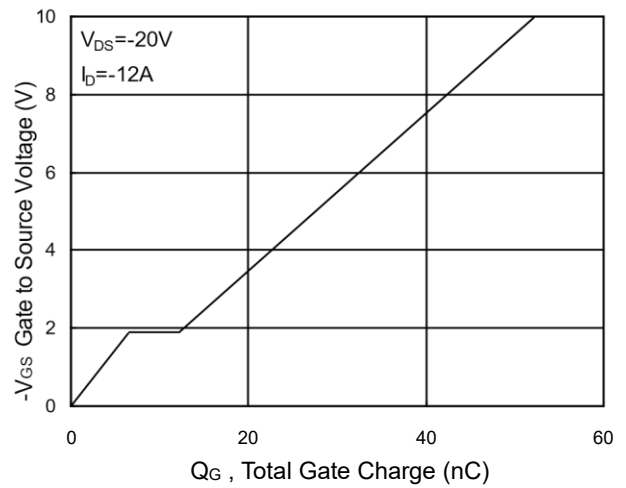


Fig.4 Gate-Charge Characteristics

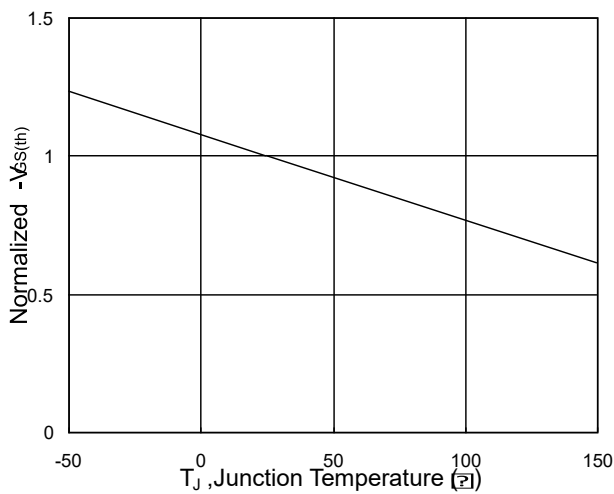


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

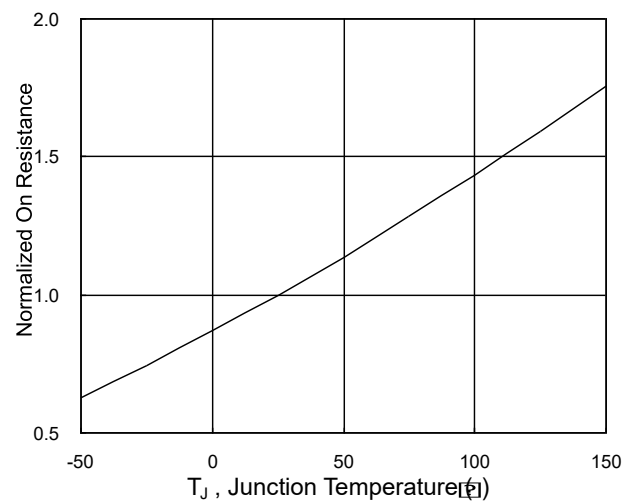


Fig.6 Normalized $R_{DS(on)}$ v.s T_J



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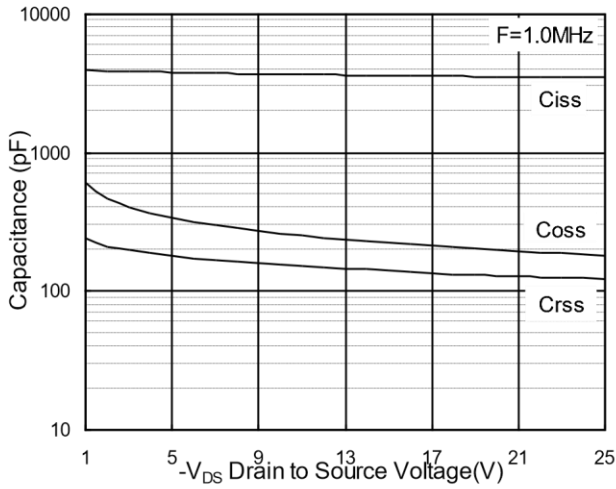


Fig.7 Capacitance

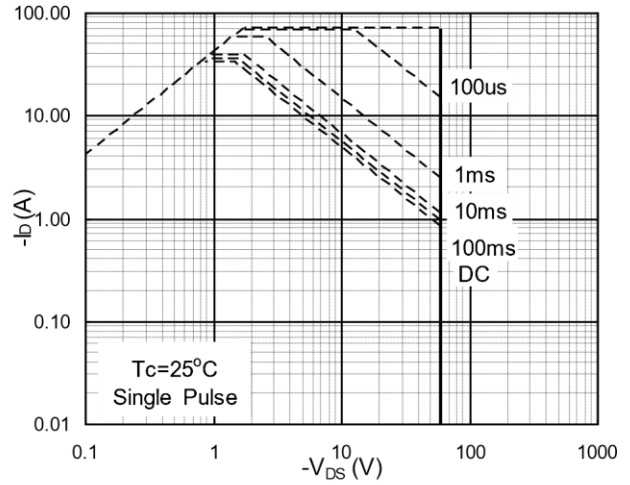


Fig.8 Safe Operating Area

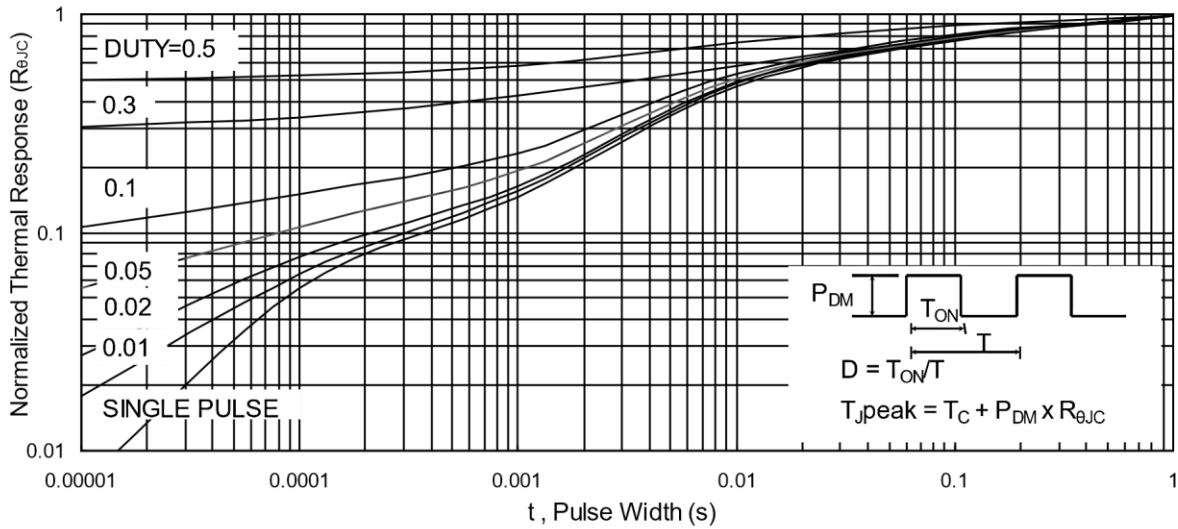


Fig.9 Normalized Maximum Transient Thermal Impedance

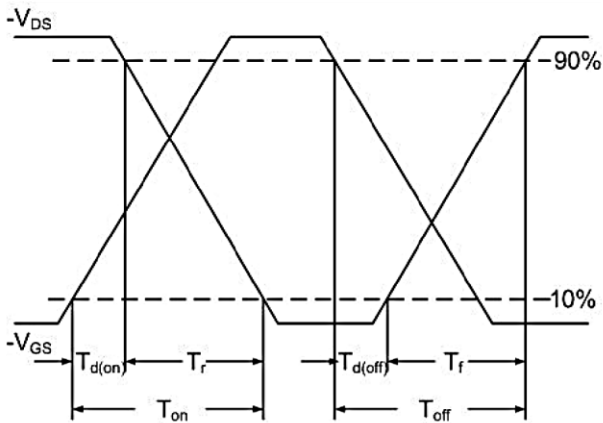


Fig.10 Switching Time Waveform

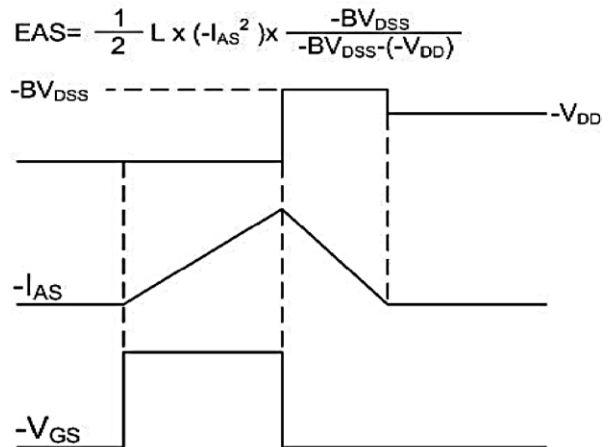
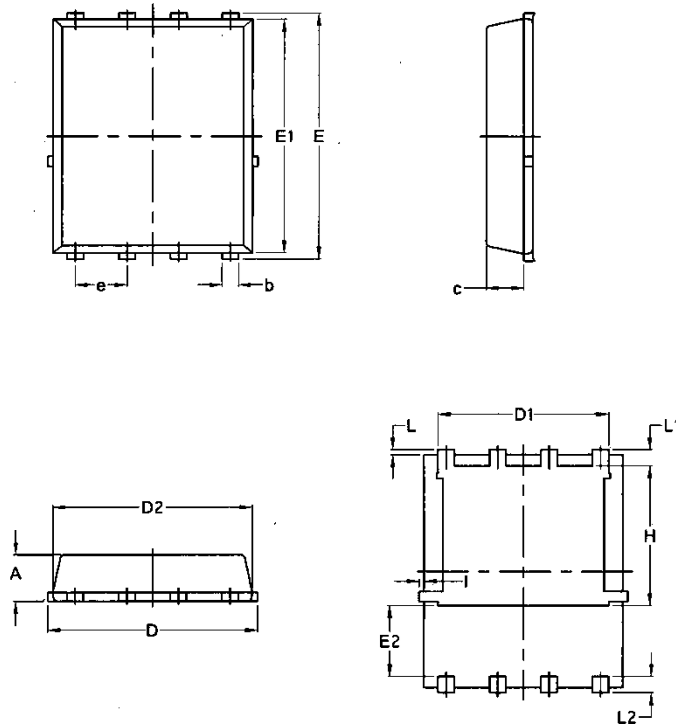


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-DFN5*6-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

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Rve1.0	2021/1/31	Initial release

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